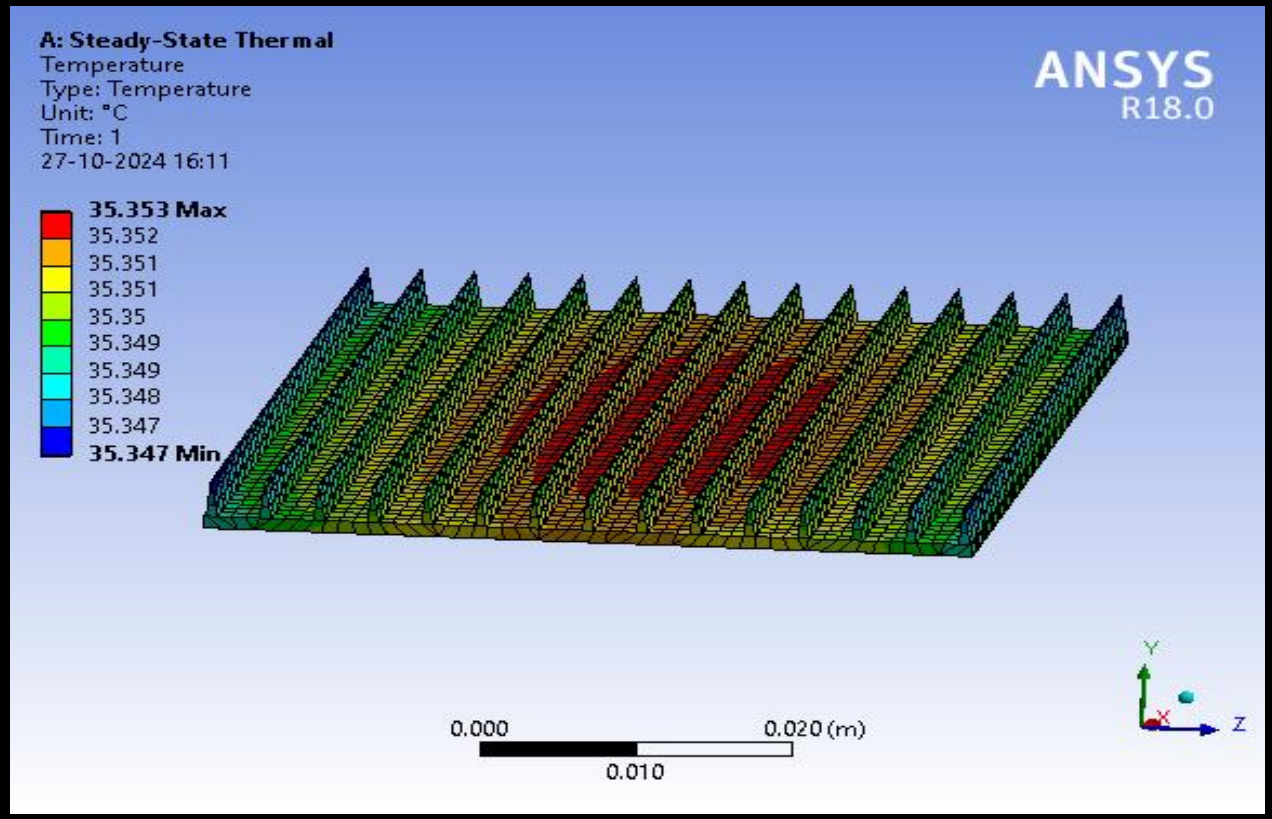
Next-gen Lightweight Graphene Heat Sinks

次世代の軽量グラフェンヒートシンク



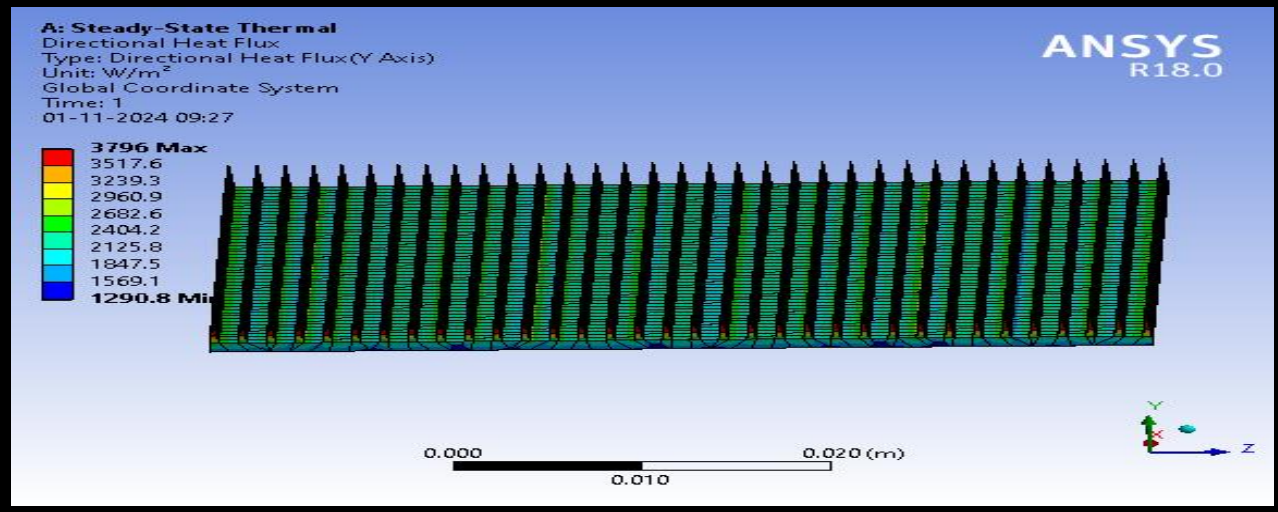
By
M. Shiva

PROJECT NEED AND ITS IMPORTANCE
このプロジェクトの必要性と重要性

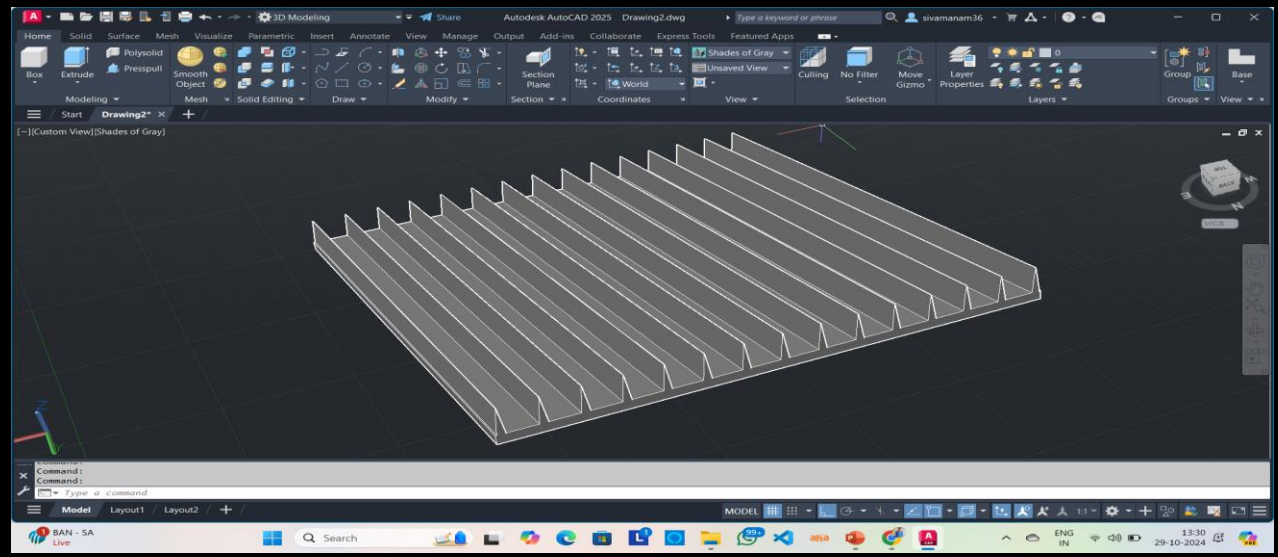
- Weight Reduction (重量削減)
- Increase Performance of Electronic Gadgets (電子機器の性能向上)
- Heat Dissipation (熱放散)
- Cost Reduction (コスト削減)

SOFTWARE'S USED
使用したソフトウェア

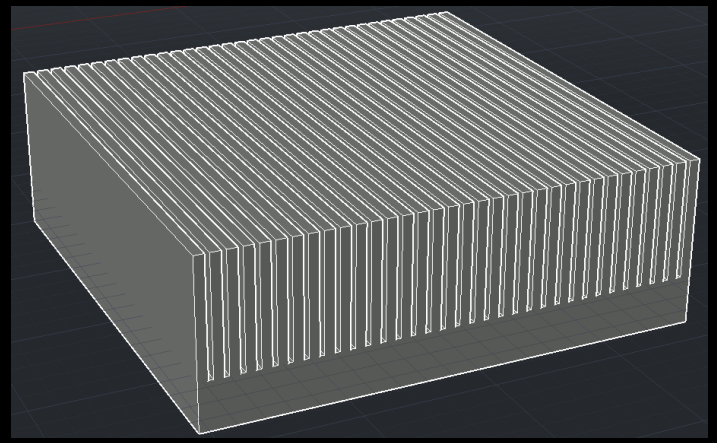
CAE Software (CAEソフトウェア)

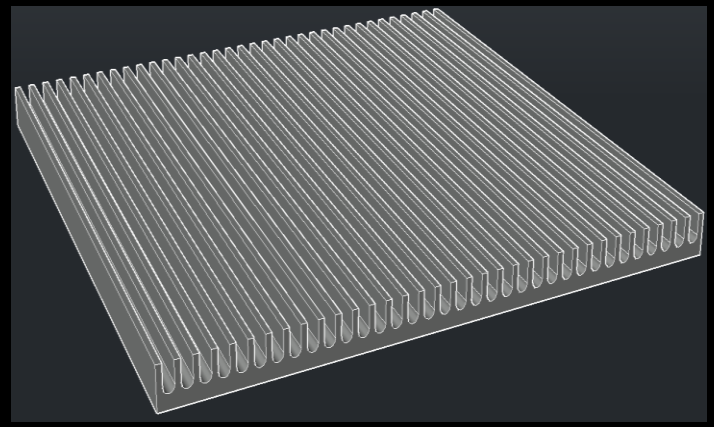


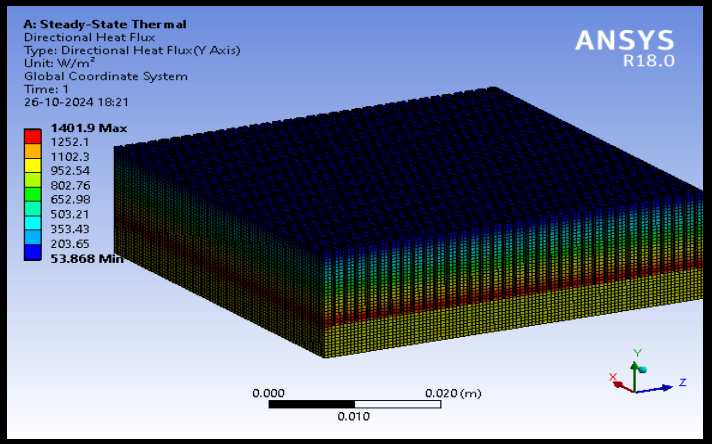
CAD Software (CADソフトウェア)

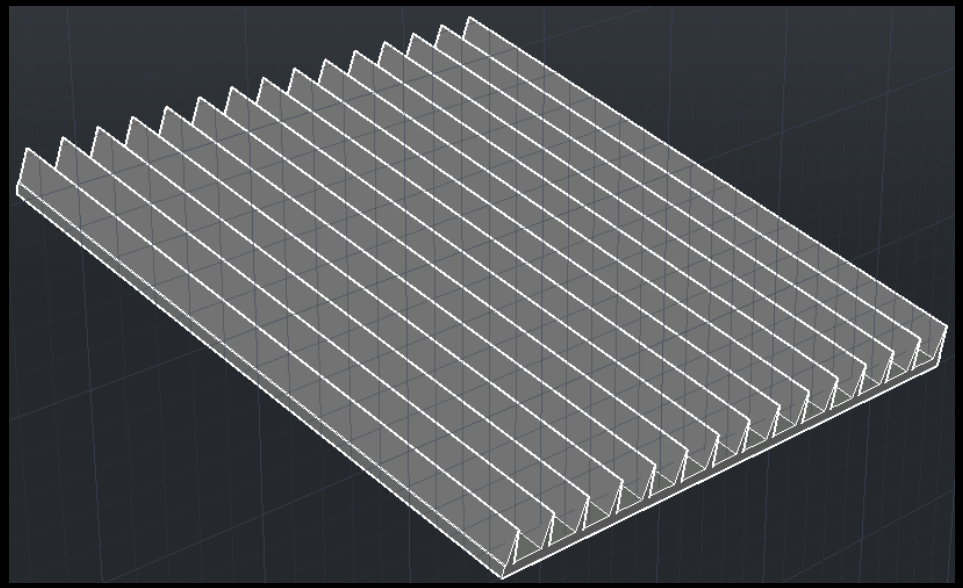


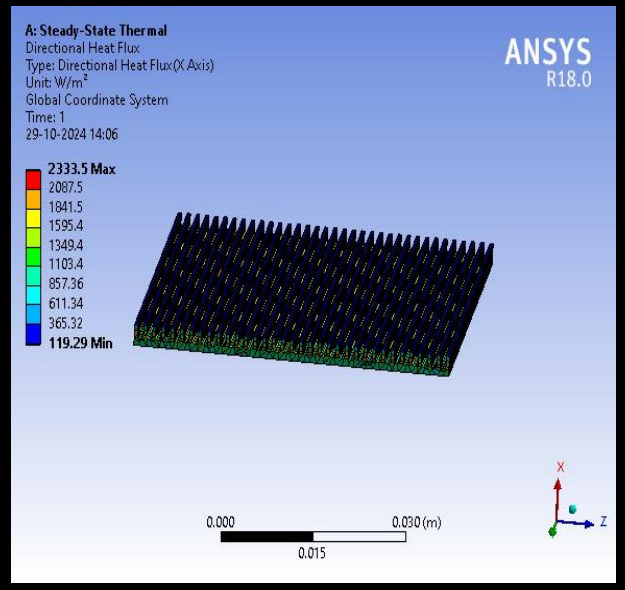
DESIGN & ANALYSIS
設計と分析

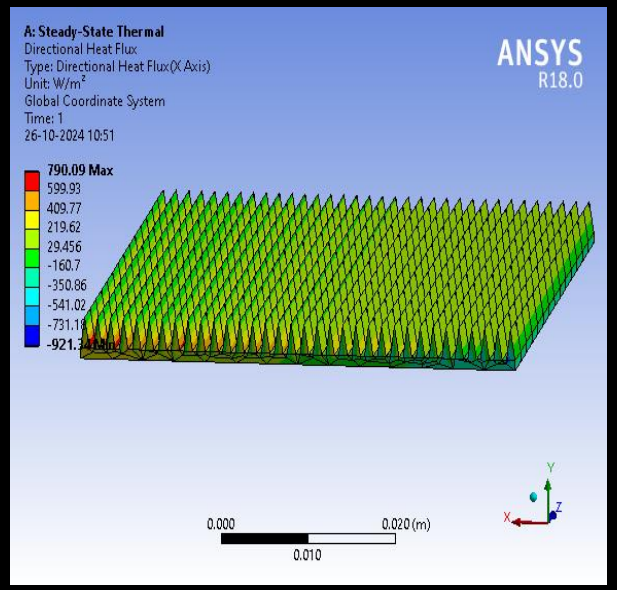










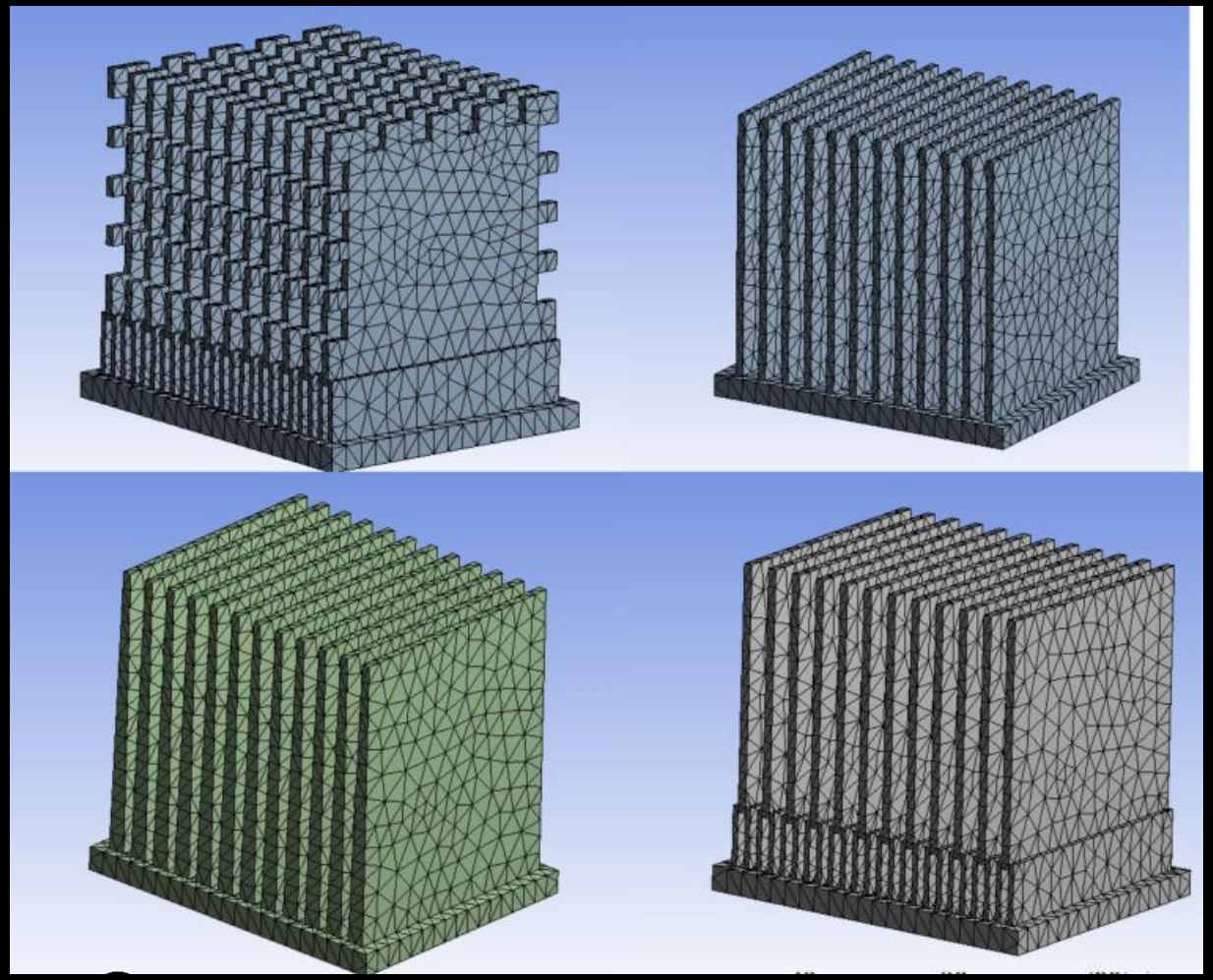


CHALLENGES FACED HEAT SINK DESIGN

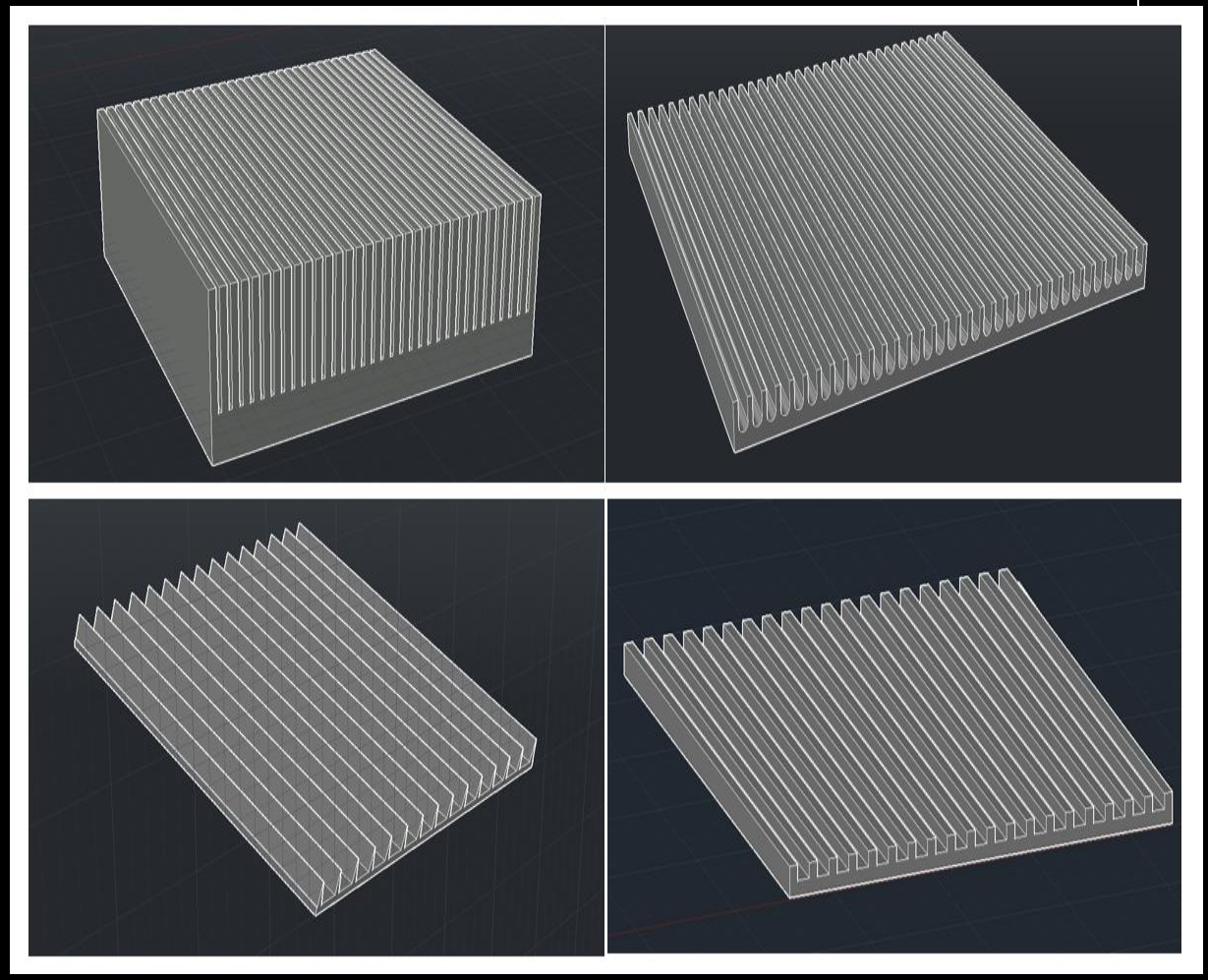
ヒートシンク設計における課題

- Material Selection (Graphene) (材料選択)
- Weight Reduction (重量削減)

RESULTS ANALYSIS
結果分析



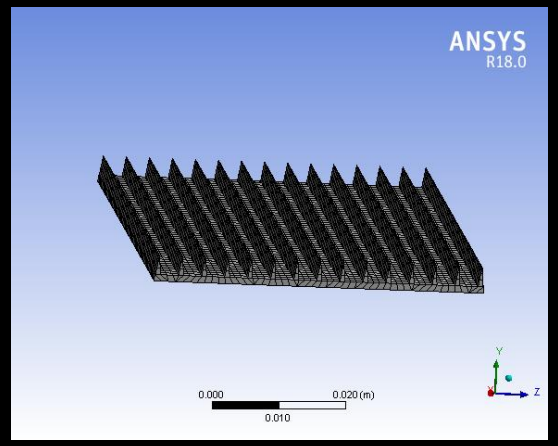
Before（前（まえ））

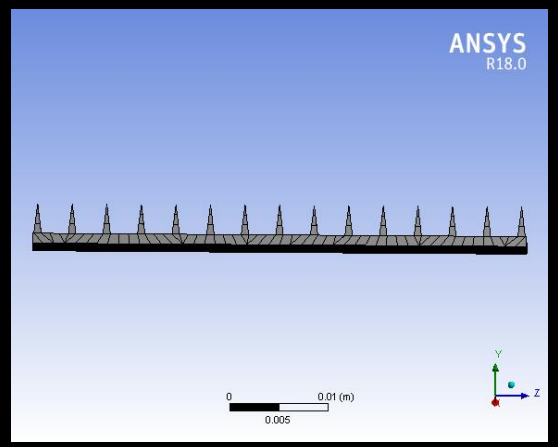


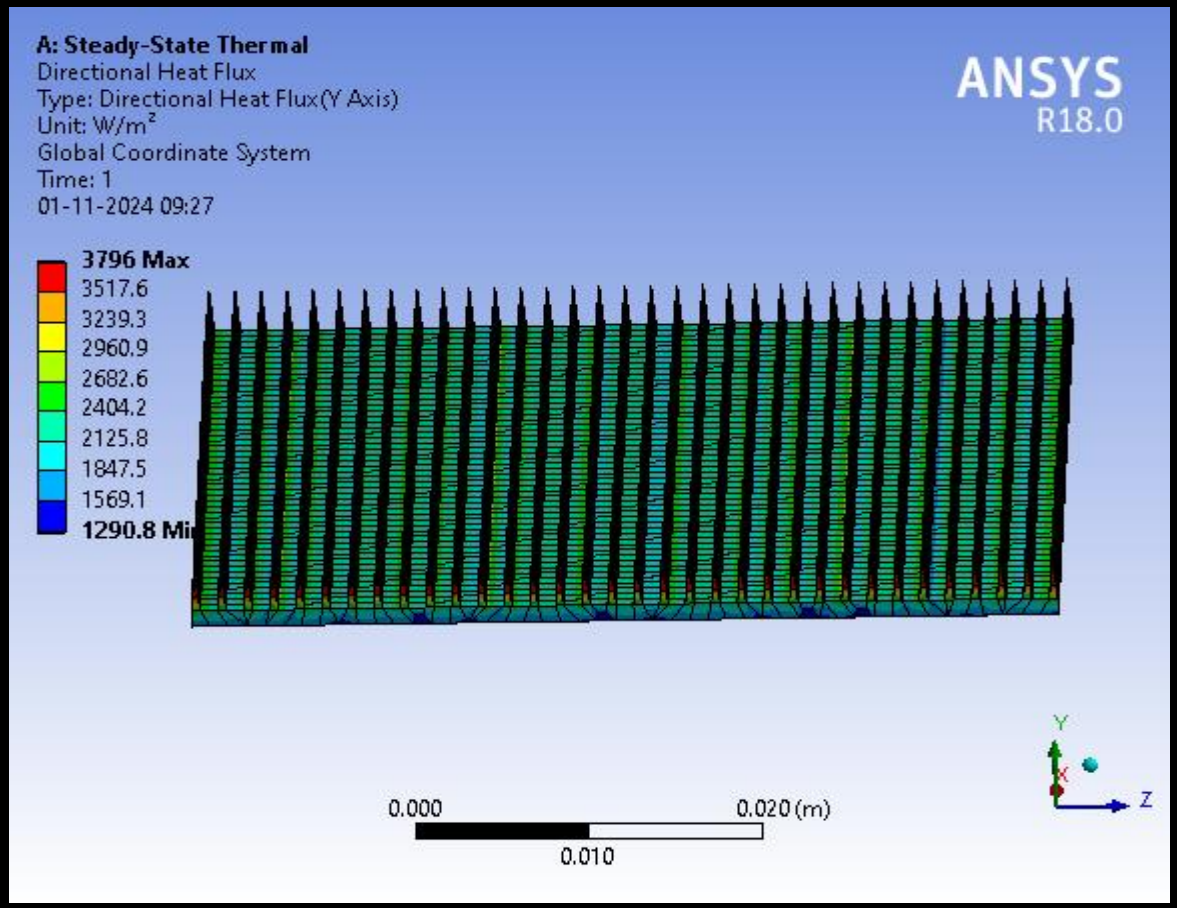
After（あと）

Final Model Identified Through Analysis with Dimensions: 0.5B - 2.5H (Gap 1(MM)

分析を通じて特定された最終モデル（寸法: 0.5B - 2.5H、ギャップ1（MM））

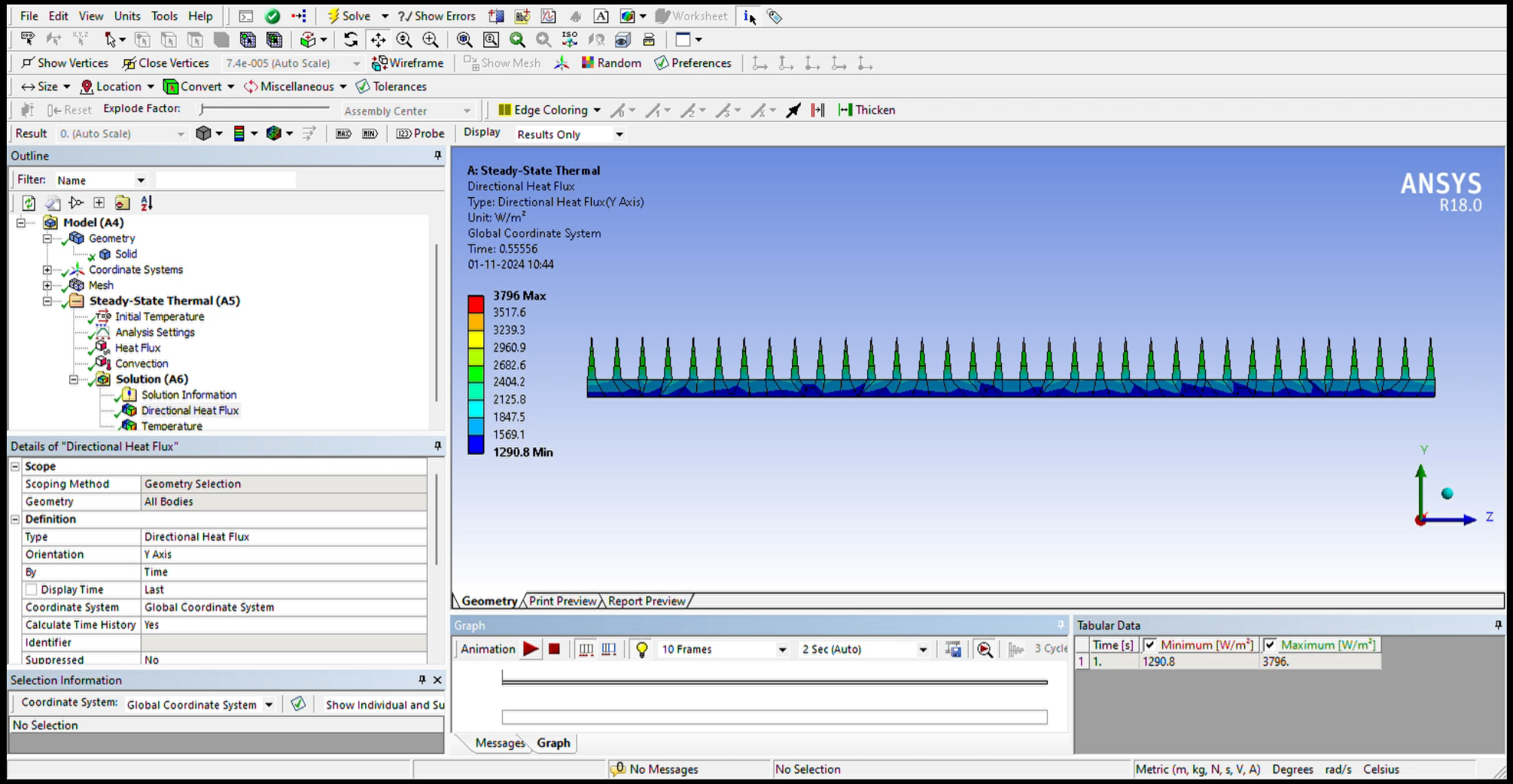






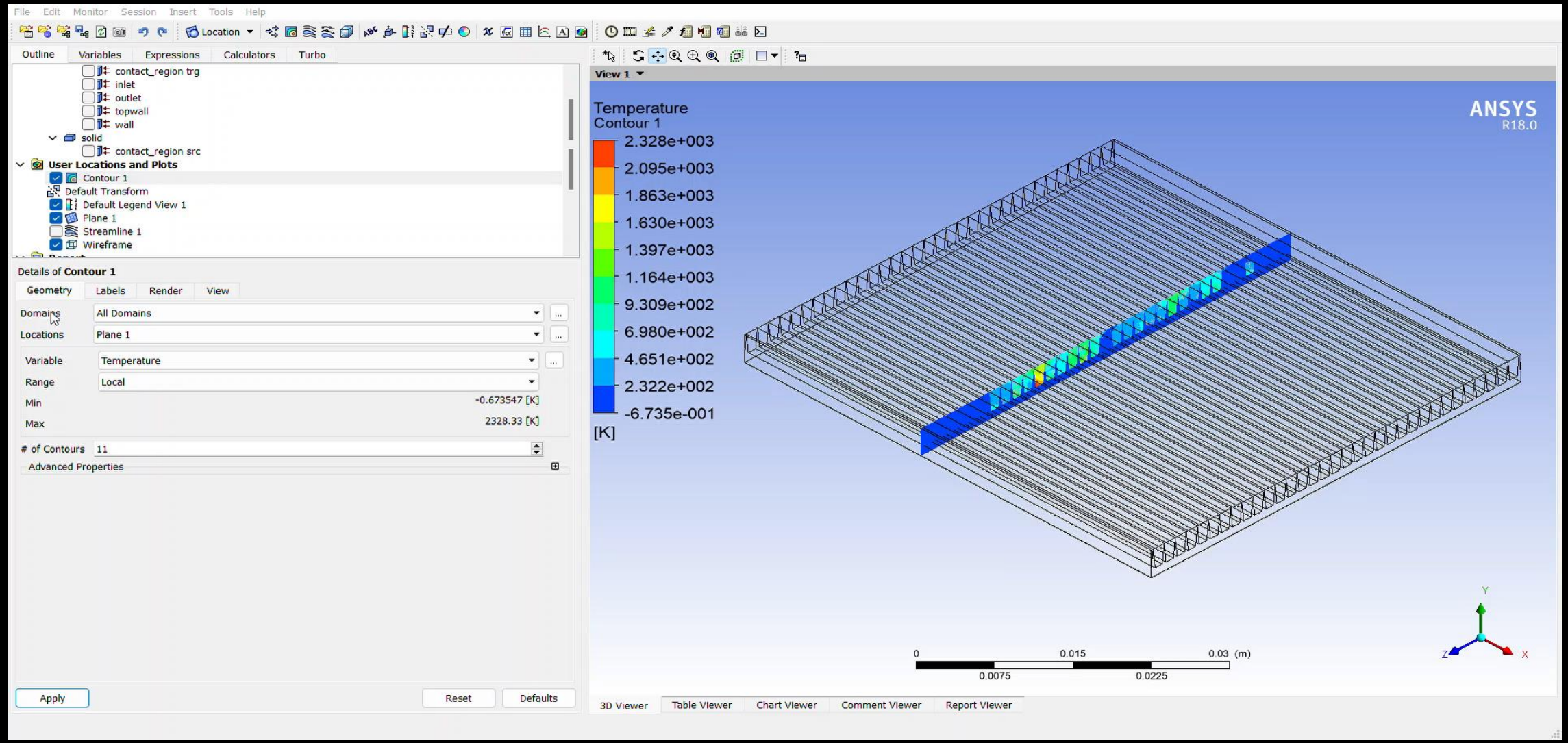
RESULTS DEMONSTRATION VIDEO

結果デモンストレーション動画



FLUID FLOW ANALYSIS

流体の流れ解析



FUTURE APPLICATIONS
将来の応用

- Automobiles (自動車（じどうしゃ))
- Renewable Energy System (再生可能エネルギーシステム)
- Electronic Gadgets (電子機器)
- Smart Home Devices (スマートホームデバイス)

THANK YOU